



Issue Date: Oct. 17, 2011

# **MR45V256A**

256k(32,768-Word × 8-Bit) FeRAM (Ferroelectric Random Access Memory) SPI

#### **GENERAL DESCRIPTION**

The MR45V256A is a nonvolatile 32,768-word x 8-bit ferroelectric random access memory (FeRAM) developed in the ferroelectric process and silicon-gate CMOS technology. The MR45V256A is accessed using Serial Peripheral Interface. Unlike SRAMs, this device, whose cells are nonvolatile, eliminates battery backup required to hold data. This device has no mechanisms of erasing and programming memory cells and blocks, such as those used for various EEPROMs. Therefore, the write cycle time can be equal to the read cycle time and the power consumption during a write can be reduced significantly.

The MR45V256A can be used in various applications, because the device is guaranteed for the write/read tolerance of 10<sup>12</sup> cycles per bit and the rewrite count can be extended significantly.

#### **FEATURES**

• 32,768-word × 8-bit configuration (Serial Peripheral Interface : SPI)

• A single 3.3 V  $\pm$  0.3 V power supply

Operating frequency: 15MHz
 Read/write tolerance 10<sup>12</sup> cycles/bit
 Data retention 10 years

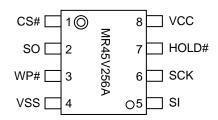
• Guaranteed operating temperature range —40 to 85°C (Extended temperature version)

• Package options:

8-pin plastic SOP (P-SOP8-200-1.27-T2K)

#### PIN CONFIGURATION

8-pin plastic SOP



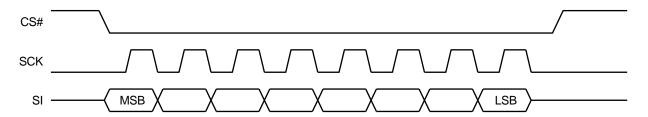
Note

Signal names that end with # indicate that the signals are negative-true logic.

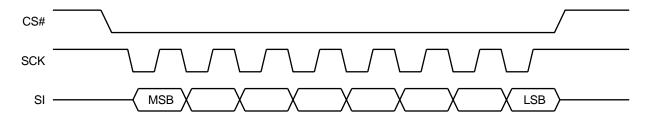
## PIN DESCRIPTIONS

Pin Name	Description
CS#	Chip Select (input, negative logic) Latches an address by low input, activates the FeRAM, and enables a read or write operation.
WP#	Write Protect( input , negative logic ) Write Protect pin controls write-operation to the status-register(BP0,BP1). This pin should be fixed low or high in write-operations.
HOLD#	HOLD( input , negative logic )  Hold pin is used when the serial-communication suspended without disable the chip select. When HOLD# is low ,the serial-output is in High-Z status and serial-input/serial-clock are "Don' t Care" . CS# should be low in hold operation.
SCK	Serial Clock Serial Clock is the clock input pin for setting for serial data timing. Inputs are latched on the rising edge and output occur on the falling edge.
SI	Serial input SI pins are serial input pins for Operation-code , addresses ,and data-inputs .
so	Serial output SO pins are serial output pins.
V <sub>CC</sub> , V <sub>SS</sub>	Power supply Apply the specified voltage to V <sub>CC</sub> . Connect V <sub>SS</sub> to ground.

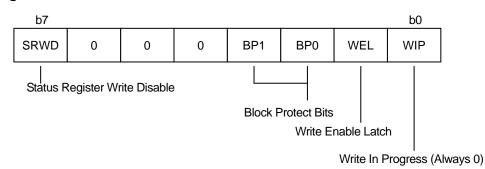
## SPI mode0 (CPOL=0, CPHA=0)



## SPI mode3 (CPOL=1, CPHA=1)



#### **Status Register**



Name	Function
WIP	Fixed to 0.
WEL	Write Enable Latch. This indicates internal WEL condition.
BP0,BP1	Block Protect :These bits can be changed protect area.
	This is the software protect.
SRWD	Status Register Write Disable (SRWD): SRWD controls the effect of the hardware WP# pin. This device will be in hardware-protect by combination of SRWD and WP#.
0	Fixed to 0.

Status Register data are volatile.

Set Status Register data by WRSR(Write status register) command, after power on.

## **Operation-Code**

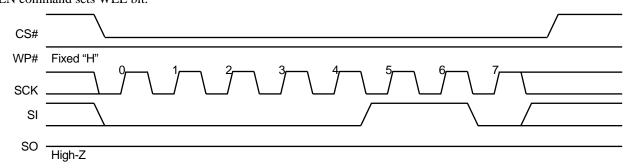
Operation codes are listed in the table below. If the device receives invalid operation code, the device will be diselected.

Instruction	Description	Instruction format
WREN	Write Enable	0000 0110
WRDI	Write Disable	0000 0100
RDSR	Read Status Register	0000 0101
WRSR	Write Status Register	0000 0001
READ	Read from Memory Array	0000 0011
WRITE	Write to Memory Array	0000 0010

#### **Commands**

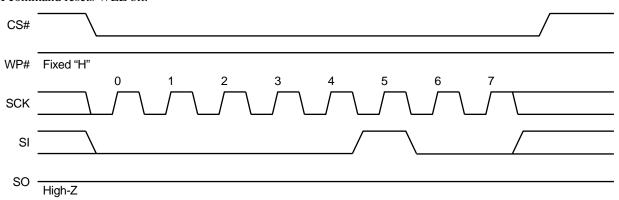
## **WREN(Write Enable)**

It is necessary to set Write Enable Latch (WEL) bit before write-operation (WRITE and WRSR). WREN command sets WEL bit.



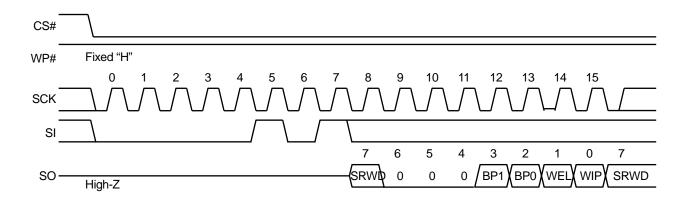
## WRDI(Write Disable)

WRDI command resets WEL bit.



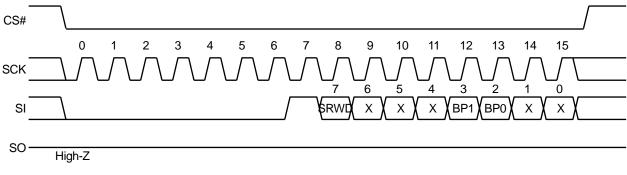
## RDSR(READ Status Register)

The RDSR command allows to read data of status register.



#### WRSR(WRITE Status Register)

WRSR command allows to write data to status register(SRWD,BP0,BP1). It is necessary to set Write Enable Latch (WEL) bit by WREN command before executing WRSR.

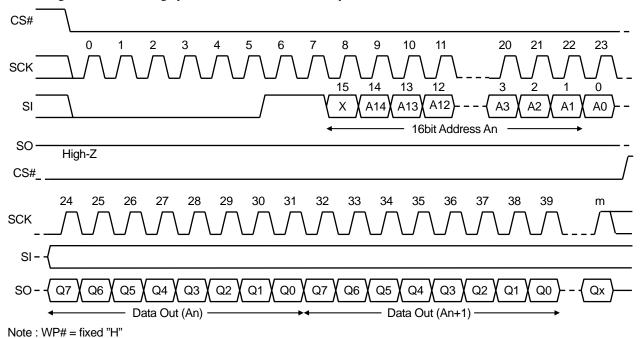


Note:

WP#=Fix "H"

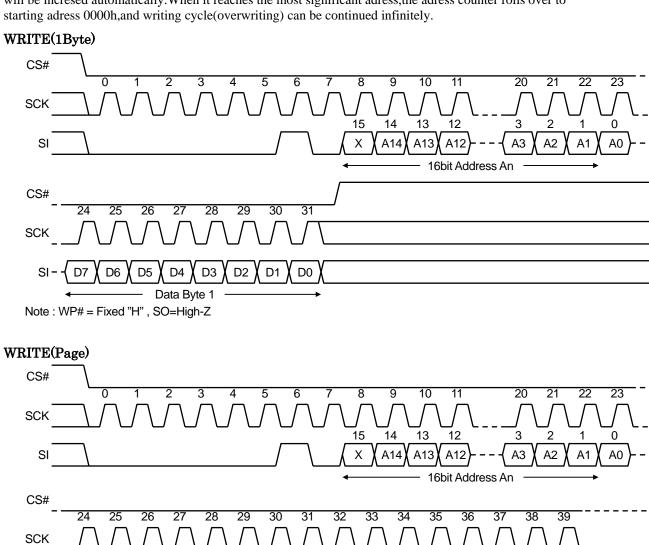
#### **READ(Read from Memory Array)**

READ command can be valid when CS# goes "L", then the op-code and 16bit-adresses are inputted to serial input"SI". The inputted adresses are loaded to internal register, then the data from corresponded address is output at serial-output "SO". If CS# will keep "L", the internal adress will be incressed automatically after 8 clocks and will output the data from new-address. When it reaches the most significant adress, the adress counter rolls over tostarting adress, and reading cycle can be continued infinitely.



#### **WRITE(Write to Memory Array)**

Write command can be valid when CS# goes "L",then the op-code and 16bit-adresses are inputted to serial input"SI". Writing is terminated when CS# goes high after data-input. If CS# will keep "L",the internal adress will be incressed automatically. When it reaches the most significant adress, the adress counter rolls over to starting adress 0000h, and writing cycle(overwriting) can be continued infinitely.



Data Byte 1 Data Byte 2 CS# 43 44 45 46 47 SCK SI-D7 D6 D5 D4 D3 D2 D1 D0 D7 D6 D4 D3 D2 D1 D0 Data Byte 3 Data Byte N

D6

D5

D4

D3

D1

D0

Note: WP# = Fixed "H", SO=High-Z

D6

D5

D4

D3

D2

D1

D0

#### **Write Protection**

Writing protection block is shown as follows:

## Protect Block size

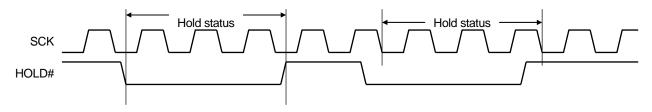
Block Protect BIT		Protected Block	Protected Address Area	
BP1	BP0	- Protected Block Protected Address Area		
0	0	None	None	
0	1	Upper 1/4 block	6000h – 7FFFh	
1	0	Upper 1/2 block	4000h – 7FFFh	
1	1	All	0000h – 7FFFh	

## Writing Protect

			Writing protection status	Protection sta	itus in memory	
WP#	SRWD	mode	in status register	Protected blocks	Unprotected blocks	
1	0	Coffusions	Status register is			
0	0	Software protection (SPM)	unprotected when WEL-bit is set by WREN command. BP0 and BP1	Protected	Unprotected	
1	1	(3:)	are unprotected.			
0	1	Hardware protection (HPM)	Status register is protected. BP0 and BP1 are protected.	Protected	Unprotected	

## **HOLD**

Hold status is used for suspending serial comunication without disable the chip. SO becomes "High-Z" and SI is "Don't care" during the hold status. It is necessary to keep CS#=L in hold status.



#### **ELECTRICAL CHARACTERISTICS**

#### **Absolute Maximum Ratings**

The application of stress (voltage, current, or temperature) that exceeds the absolute maximum rating may damage the device. Therefore, do not allow actual characteristics to exceed any one parameter ratings

#### Pin voltages

Parameter	Symbol	Ra	Unit	
Falameter	Symbol	Min.	Max.	Offic
Pin Voltage (Input Signal)	V <sub>IN</sub>	-0.5	V <sub>CC</sub> + 0.5	V
Pin Voltage (Input/Output Voltage)	V <sub>INQ</sub> , V <sub>OUTQ</sub>	-0.5	V <sub>CC</sub> + 0.5	V
Power Supply Voltage	V <sub>CC</sub>	-0.5	4.0	V

**Temperature Range** 

Parameter	Symbol	Rat	ting	Unit	Note	
Farameter	Symbol	Min.	Max.	Offic		
Storage Temperature (Extended Temperature Version)	Tstg	<b>–</b> 55	125	°C		
Operating Temperature (Extended Temperature Version)	Topr	-40	85	°C		

#### Others

Parameter	Symbol	Rating	Unit
Power Dissipation	$P_{D}$	1,000mW	
Allowable Input Current	Allowable Input Current I <sub>IN</sub>		Ta=25°C
Allowable Output Current	I <sub>OUT</sub>	+/- 20mA	Ta=25°C

## **Recommended Operating Conditions**

## **Power Supply Voltage**

[V]

Parameter	Symbol	Min.	Тур.	Max.	Note
Power Supply Voltage	V <sub>CC</sub>	3.0	3.3	3.6	
Ground Voltage	V <sub>SS</sub>	0	0	0	

## **DC Input Voltage**

[V]

Parameter	Symbol	Min.	Max.	Note
Input High Voltage	V <sub>IH</sub>	V <sub>CC</sub> x 0.8	V <sub>CC</sub> +0.3	
Input Low Voltage	$V_{IL}$	-0.3	V <sub>CC</sub> x 0.2	

#### Overshoot/Undershoot tolerance

Parameter	Symbol	Pulse Width	Peak
"H" input	V <sub>IH</sub> OVERSHOOT	≤ 20ns	V <sub>CC</sub> +1.0V
"L" input	V <sub>IL UNDERSHOOT</sub>	≤ 20ns	– 1.0V

#### **DC** Characteristics

**DC Input/Output Characteristics** 

input Output Characteristics									
Parameter	Symbol	Condition	Min.	Max.	Unit	Note			
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> =-2mA	V <sub>CC</sub> × 0.85	1	٧				
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> =2mA	_	V <sub>CC</sub> × 0.15	V				
Input Leakage Current	I <sub>LI</sub>	_	-10	10	μΑ				
Output Leakage Current	I <sub>LO</sub>	_	-10	10	μΑ				

## **Power Supply Current**

 $V_{CC}$ =Max.to Min, Ta=Topr

Parameter	Symbol	Condition	Max.	Unit	Note
Power Supply Current (Standby)	I <sub>ccs</sub>	V <sub>IN</sub> =0.2V or V <sub>CC</sub> -0.2V	400	μΑ	
Power Supply Current (Operating)	I <sub>CCA</sub>	$V_{\rm IN}$ =0.2V or $V_{\rm CC}$ -0.2V, SCK=15MHz, $I_{\rm OUT}$ =0mA	10	mA	

## **AC Characteristics (Read Cycle)**

 $V_{CC}$ =Max. to Min., Ta=Topr.

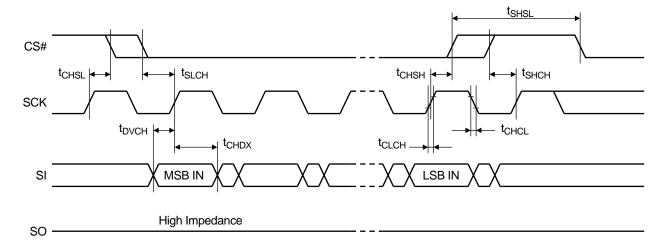
_	Symbol	MR45	11.20	<b>N.</b> .	
Parameter		Min.	Max.	Unit	Note
Clock frequency	f <sub>C</sub>	D.C.	15	MHz	
CS# Active setup time	t <sub>SLCH</sub>	10		ns	
CS# In-active setup-time	t <sub>SHCH</sub>	10	_	ns	
CS# De-select time	t <sub>SHSL</sub>	10	_	ns	
CS# Active hold time	t <sub>CHSH</sub>	10	_	ns	
CS# In-active hold-time	t <sub>CHSL</sub>	10	_	ns	
SCK High time	t <sub>CH</sub>	30	_	ns	1
SCK Low time	t <sub>CL</sub>	30	_	ns	1
SCK Rise time	t <sub>CLCH</sub>	_	1	ns	2
SCK Fall time	t <sub>CHCL</sub>	_	1	ns	2
Data Setup time	t <sub>DVCH</sub>	5	_	ns	
Data Hold time	t <sub>CHDX</sub>	5	_	ns	
SCK Low Hold time after HOLD# inactive	t <sub>HHCH</sub>	10	_	ns	
SCK Low Hold time after HOLD# active	t <sub>HLCH</sub>	10	_	ns	
SCK High Setup time before HOLD# active	t <sub>CHHL</sub>	10	<del></del>	ns	
SCK High Setup time before HOLD# inactive	t <sub>CHHH</sub>	10		ns	
Output disable time	t <sub>SHQZ</sub>	_	20	ns	2
SCK Low to Output Valid time	t <sub>CLQV</sub>		35	ns	
Output Hold time	t <sub>CLQX</sub>	0	_	ns	
Output Rise time	t <sub>QLQH</sub>	_	50	ns	2
Output Fall time	t <sub>QHQL</sub>	_	50	ns	2
HOLD# High to Output Low impedance time	t <sub>HHQX</sub>	_	20	ns	2
HOLD# High to Output High impedance time	t <sub>HLQZ</sub>	_	20	ns	2

Note:  $1. t_{CH} + t_{CL} \ge 1/f_C$ 

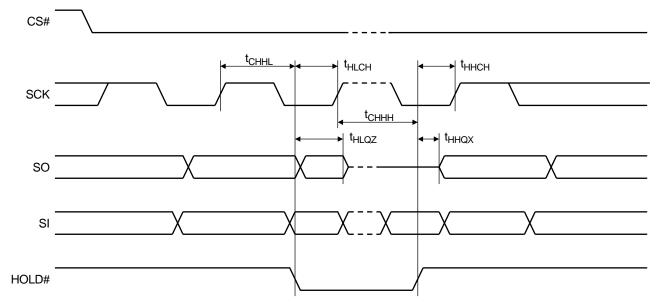
2. sample value

#### **Timing Diagrams**

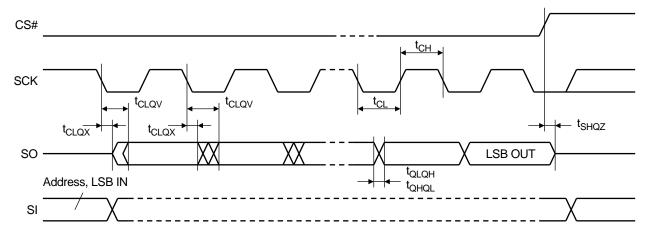
#### **Serial Input Timing**



#### **Hold Timing**



## **Output Timing**



## LAPIS Semiconductor Co., Ltd.

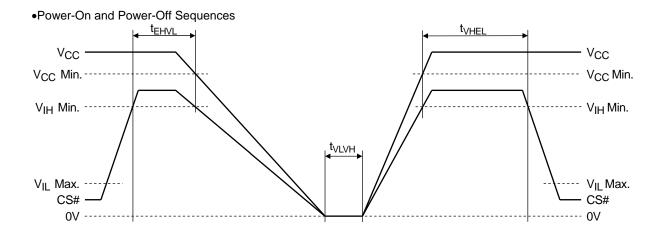
#### •Power-On and Power-Off Characteristics

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Parameter	Symbol	Min.	Max.	Unit	Note
Power-On CS# High Hold Time	t <sub>VHEL</sub>	50	_	μS	1, 2
Power-Off CS# High Hold Time	t <sub>EHVL</sub>	100	_	ns	1
Power-On Interval Time	t <sub>VLVH</sub>	1		μS	2

#### Notes:

- 1. To prevent an erroneous operation, be sure to maintain CS#="H", and set the FeRAM in an inactive state (standby mode) before and after power-on and power-off.
- 2. Powering on at the intermediate voltage level will cause an erroneous operation; thus, be sure to power up from  $0\ V$ .
- 3. Enter all signals at the same time as power-on or enter all signals after power-on.



## Read/Write Cycles and Data Retention

(Under recommended operating conditions)

Parameter	Min.	Max.	Unit	Note
Read/Write Cycle	10 <sup>12</sup>	_	Cycle	_
Data Retention	10	_	Year	_

#### Capacitance

Signal	Symbol	Min.	Max.	Unit	Note
Input Capacitance	C <sub>IN</sub>	_	10	pF	1
Input/Output Capacitance	Соит	_	10	pF	1

Note:

Sampling value. Measurement conditions are  $V_{\text{IN}} = V_{\text{OUT}} = GND$ , f = 1MHz, and  $Ta = 25^{\circ}C$ 

## **REVISION HISTORY**

		Page			
Document No.	Date	Previous Edition	Current Edition	Description	
PEDR45V256A-01	Jun. 03, 2010	-	-	Preliminary edition 1 from PJDR45V256A-03	
		1,13	1,13	Input Voltage	
PEDR45V256A-02	Sep. 10, 2010	7,8,9	7,8,9	fixed CS# waveform	
		14	14	Iccs Icca	
PEDR45V256A-03	Mar. 04, 2011	1,12	1,12	temperature version $\Rightarrow$ Extended version	
PEDR45V256A-04	Sep. 05, 2011	4 17	4 17	Status Register Input signal state in power-on	
PEDR45V256A-05	Oct. 17, 2011	1-20	1-20	Changed corporate name and logo to LAPIS Semiconductor.	

#### **NOTES**

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